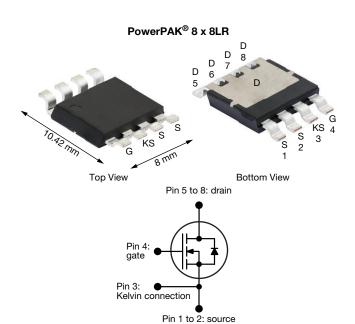
COMPLIANT

HALOGEN

**FREE** 



# **E Series Power MOSFET**



PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.104		
Q <sub>g</sub> max. (nC)	44			
Q <sub>gs</sub> (nC)	13			
Q <sub>gd</sub> (nC)	7			
Configuration	Single			

N-Channel MOSFET

### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure of merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

## **APPLICATIONS**

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8LR
Lead (Pb)-free and halogen-free	SiHR120N60E-T1-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			$V_{DS}$	600	V	
Gate-source voltage			$V_{GS}$	± 30	V	
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C		32	A	
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	I <sub>D</sub>	20		
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	53	1	
Linear derating factor				2.2	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	144	mJ	
Maximum power dissipation			$P_{D}$	278	W	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C		
Drain-source voltage slope		dv/dt	100	V/ns		
Reverse diode dv/dt <sup>d</sup>			22			

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD} = 120 \text{ V}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ ,  $L = 28.2 \,\text{mH}$ ,  $R_q = 25 \,\Omega$ ,  $I_{AS} = 3.2 \,\text{A}$
- c.  $I_{SD} \leq I_{D}$ , di/dt = 100 A/ $\mu$ s, starting  $T_{J}$  = 25 °C

S23-0991-Rev. A, 20-Nov-2023



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	$R_{thJA}$	-	42	°C/W	
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.45	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static					•		
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I <sub>D</sub> = 1 mA		0.61	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		-	5.0	V
Cata aguirra laglaga		V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-source leakage	$I_{GSS}$	,	$V_{GS} = \pm 30 \text{ V}$		-	± 1	μA
Zava gata valtaga dvain avvvant		V <sub>DS</sub> =	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V		-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 8 A	-	0.104	0.120	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 8 V, I <sub>D</sub> = 11 A		-	13	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V,		-	1900	-	pF
Output capacitance	C <sub>oss</sub>		V <sub>DS</sub> = 100 V,		74	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 100 kHz		-	1	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V		-	71	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>			-	437	-	
Total gate charge	Qg			-	29	44	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 11 \text{ A}, V_{DS} = 480 \text{ V}$		13	-	nC
Gate-drain charge	Q <sub>gd</sub>				7	-	
Turn-on delay time	t <sub>d(on)</sub>	·		-	23	46	- ns
Rise time	t <sub>r</sub>	V <sub>DD</sub> =	$V_{DD} = 480 \text{ V}, I_{D} = 11 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		32	64	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =			22	44	
Fall time	t <sub>f</sub>	1		-	19	38	
Gate input resistance	$R_g$	f = 1 MHz		0.3	0.7	1.4	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	32	
Pulsed diode forward current	I <sub>SM</sub>			-	-	53	A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 11 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse recovery time	t <sub>rr</sub>	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 11 \text{A},$ $di/dt = 100 \text{A/}\mu\text{s}, V_R = 25 \text{V}$		-	299	598	ns
Reverse recovery charge	Q <sub>rr</sub>			-	3.9	7.8	μC
Reverse recovery current	I <sub>RRM</sub>			_	23	-	Α



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

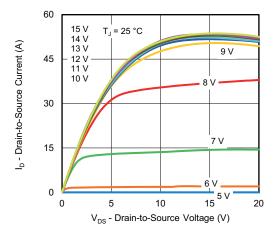


Fig. 1 - Typical Output Characteristics

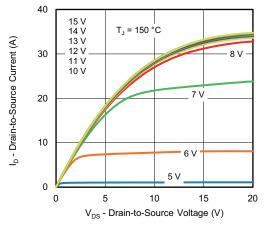


Fig. 2 - Typical Output Characteristics

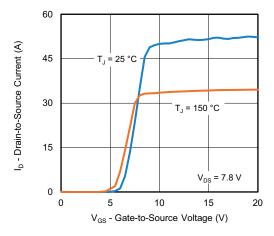


Fig. 3 - Typical Transfer Characteristics

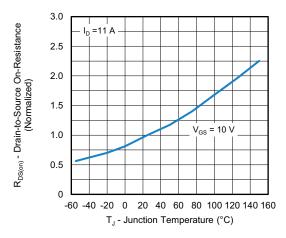


Fig. 4 - Normalized On-Resistance vs. Temperature

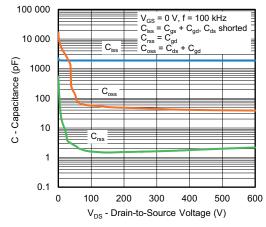


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

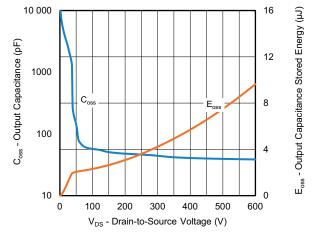


Fig. 6 - Coss and Eoss vs. VDS



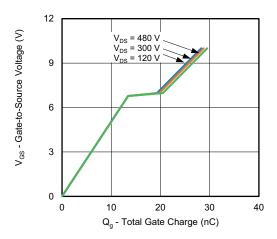


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

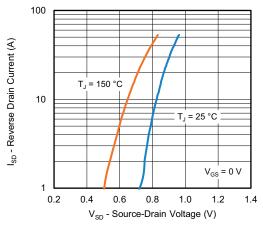


Fig. 8 - Typical Source-Drain Diode Forward Voltage

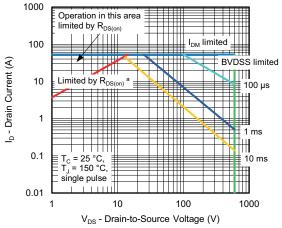


Fig. 9 - Maximum Safe Operating Area



a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

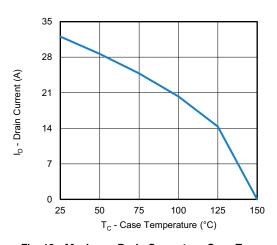


Fig. 10 - Maximum Drain Current vs. Case Temperature

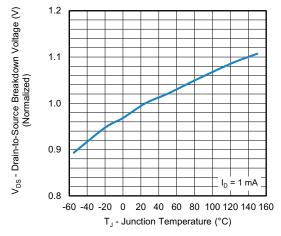


Fig. 11 - Temperature vs. Drain-to-Source Voltage



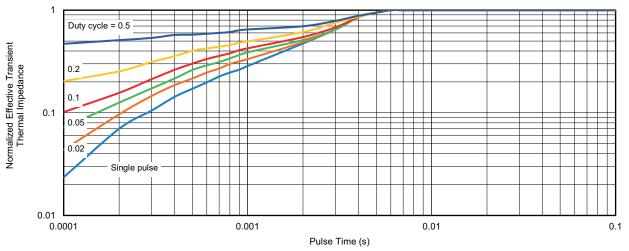


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

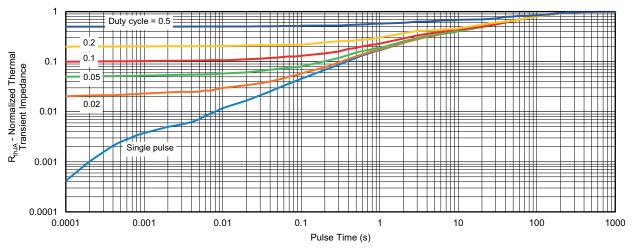


Fig. 13 - Normalized Transient Thermal Impedance, Junction-to-Ambient

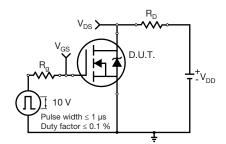


Fig. 14 - Switching Time Test Circuit

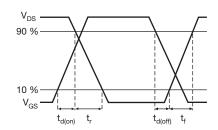


Fig. 15 - Switching Time Waveforms



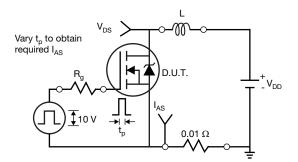


Fig. 16 - Unclamped Inductive Test Circuit

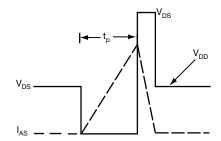


Fig. 17 - Unclamped Inductive Waveforms

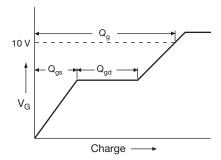


Fig. 18 - Basic Gate Charge Waveform

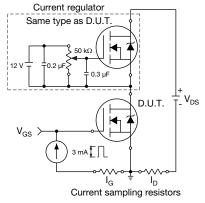
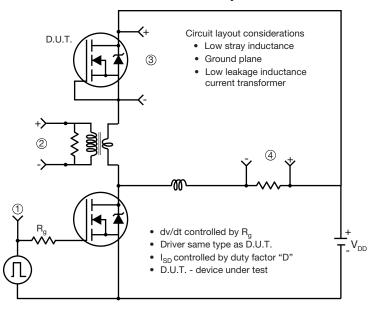


Fig. 19 - Gate Charge Test Circuit



## Peak Diode Recovery dv/dt Test Circuit



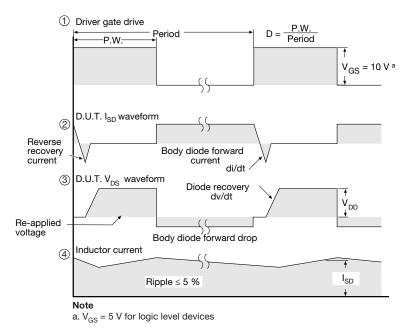


Fig. 20 - For N-Channel

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